

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	751	(semiconductor or chip) and RESURF	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 12:47
S2	622	S1 and (breakdown)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 13:19
S3	333	S2 and impurity	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 13:19
S4	183	S3 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 16:20
S5	78	S4 and @pd < "20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 13:29
S6	43	S5 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 13:30
S9	751	(semiconductor or chip) and RESURF	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 13:09
S10	622	S9 and (breakdown)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 10:02
S11	333	S10 and impurity	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 10:02
S12	183	S11 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 10:02

S13	78	S12 and @pd < "20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 10:02
S14	43	S13 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 10:02
S15	43	S14	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:04
S16	96	S9 and (leakage adj current)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:04
S17	95	S16 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:24
S18	1	("4044373").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 11:24
S19	491	(257/499).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 11:27
S20	65	S19 and (isolation adj region)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:28
S21	39	S20 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:28
S22	21	S21 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:30

S23	374	S19 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:31
S24	353	S23 not S22	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:31
S25	132	S24 and current	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:31
S26	25	S25 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:36
S27	26	S25 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:36
S28	21	S27 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:38
S29	46	S28 or S27 or S26	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:39
S30	89	S28 or S27 or S26 or S14	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:39
S31	160	RESURF and (breakdown adj voltage) and buried and isolation	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/09/23 11:40
S32	159	S31 and (chip or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 11:41

S33	145	S32 not S30	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 16:20
S34	66	S33 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 12:40
S35	1	("6084263").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:41
S36	1	("6707104").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:46
S37	1	("6100549").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:47
S38	1	("6362064").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:48
S39	1	("6867456").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:49
S40	1	("5640034").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:50
S41	1	("5569949").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:51
S42	1	("20020113286").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:57

S43	1	("20020113286").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 12:57
S44	4	S9 and (trench near current)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 13:10
S45	81	S9 and (trench with current)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 13:10
S46	77	S45 not S44	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 13:20
S47	1	("20020100935").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 13:27
S48	1	("20030047776").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 13:30
S49	1	("5637898").PN.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/09/23 13:42
S50	327	(semiconductor or chip)and (trench with isolation) and (breakdown adj voltage) and (leakage adj current)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 13:47
S51	159	(semiconductor or chip)and (trench with isolation) and (breakdown adj voltage) and (leakage adj current)and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:06
S52	92	(trench adj capacitor) and (breakdown adj voltage) and (leakage adj current) and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:06

S53	57	(trench adj capacitor) and (breakdown adj voltage) and (leakage adj current) and trench and (chip or semiconductor) and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:24
S54	253	(trench adj isolation) and (breakdown adj voltage) and (leakage adj current) and trench and (chip or semiconductor) and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:30
S55	253	S54 notL49	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:24
S56	226	S54 not S53	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:25
S57	226	S54 not (S53 and S52)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:25
S58	1	(trench near conductor) and (breakdown adj voltage) and (leakage adj current) and trench and (chip or semiconductor) and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:31
S59	94	(trench near (metal or silicon or conduct\$4)) and (breakdown adj voltage) and (leakage adj current) and trench and (chip or semiconductor) and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/23 14:32
S60	102	hvic and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 16:21
S61	124	hvic and (semiconductor or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 17:02
S62	2294	(chip or semiconductor) and gate and ((trench near substrate) or (trench with substrate)) and (leakage near current) and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 17:04

S63	2293	S62 not S61	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 17:04
S64	65	S63 and (field near plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/30 17:04
S65	618	(257/339).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:14
S66	422	(257/343).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 08:20
S69	86	(257/489).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:42
S70	110	(257/490).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:53
S71	185	(257/491).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S72	195	(257/492).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S73	182	(257/493).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S74	202	(257/494).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12

S75	232	(257/495).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S76	1197	(257/506).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S77	244	(257/509).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:12
S78	844	(257/510).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S79	309	(257/513).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S80	152	(257/514).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S81	339	(257/544).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S82	378	(257/500).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S83	412	(257/508).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/03 16:13
S85	502	S65 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/03 16:15

S86	263	(257/337).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:05
S87	254	(257/488).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:06
S88	218	S87 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 09:41
S89	86	(257/489).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:42
S90	70	S89 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 09:52
S91	110	(257/490).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 09:53
S92	89	S91 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 10:15

S93	62	(US-20020027259-\$ or US-20020030226-\$ or US-20020043699-\$ or US-20020102808-\$ or US-20020113286-\$ or US-20020179974-\$ or US-20020195659-\$ or US-20030168710-\$ or US-20030214009-\$ or US-20040124464-\$ or US-20050056906-\$ or US-20050144539-\$ or US-20050146823-\$ or US-20050169026-\$ or US-20050179089-\$ or US-20050194656-\$ or US-20020017683-\$ or US-20010009287-\$).did. or (US-4661838-\$ or US-4890146-\$ or US-4933739-\$ or US-5021852-\$ or US-5485027-\$ or US-5514608-\$ or US-5624858-\$ or US-5637898-\$ or US-5793065-\$ or US-5912495-\$ or US-5925900-\$ or US-5986301-\$ or US-6037634-\$ or US-6124628-\$ or US-6198130-\$ or US-6246101-\$ or US-6252258-\$ or US-6323509-\$ or US-6323539-\$ or US-6507085-\$ or US-6586780-\$ or US-6603176-\$ or US-6707104-\$ or US-6750524-\$ or US-6864550-\$ or US-6927455-\$). did. or (US-6552389-\$ or US-6501129-\$ or US-6445019-\$ or US-6194761-\$ or US-5742087-\$ or US-5525821-\$ or US-5191396-\$ or US-4707720-\$ or US-6924531-\$ or US-6806533-\$ or US-5598018-\$ or US-4949142-\$ or US-6064074-\$ or US-5914523-\$ or US-5898199-\$ or US-4868921-\$ or US-5113237-\$ or US-5233215-\$).did.	US-PGPUB; USPAT	OR	OFF	2005/10/04 10:28
S94	185	(257/491).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 10:28
S95	140	S94 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04

S96	755	(semiconductor or chip) and RESURF	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S97	625	S96 and (breakdown)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S98	335	S97 and impurity	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S99	183	S98 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 0	78	S99 and @pd < "20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 1	43	S100 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 2	755	(semiconductor or chip) and RESURF	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 3	625	S102 and (breakdown)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 4	335	S103 and impurity	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 5	183	S104 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04

S10 6	78	S105 and @pd < "20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 7	43	S106 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S10 8	492	(257/499).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S10 9	65	S108 and (isolation adj region)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 0	39	S109 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 1	21	S110 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 2	374	S108 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 3	353	S112 not S111	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 4	132	S113 and current	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 5	25	S114 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04

S11 6	26	S114 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 7	21	S116 not S115	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 8	46	S117 or S116 or S115	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S11 9	89	S117 or S116 or S115 or S107	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 0	161	RESURF and (breakdown adj voltage) and buried and isolation	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 1	160	S120 and (chip or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S12 2	146	S121 not S119	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S12 3	66	S122 and @pd<"20030520"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 13:04
S12 4	86	(257/489).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 5	70	S124 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04

S12 6	110	(257/490).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 7	89	S126 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 8	185	(257/491).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S12 9	140	S128 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:04
S13 0	7757	(S101 or "S125" or S111 or "S96" or S125 or S127 or S129 or S123 or S119 or S118)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:06
S13 1	3273	(257/506,509,510,513,514,544,500, 508).CCLS.	US-PGPUB; USPAT; USOCR; JPO; IBM_TDB	OR	OFF	2005/10/04 13:07
S13 3	2566	S131 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:07
S13 4	2517	S133 not S130	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:19
S13 5	781	S134 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:19
S13 6	331	S135 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 13:20

S13 7	59	S135 and trench and plate	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/10/04 14:10
S13 8	755	(semiconductor or chip)and RESURF	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 14:11
S13 9	373	S138 and buried	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 14:11
S14 0	173	S139 and trench	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 14:11
S14 1	69	S140 and @pd<"20030503"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/10/04 14:11